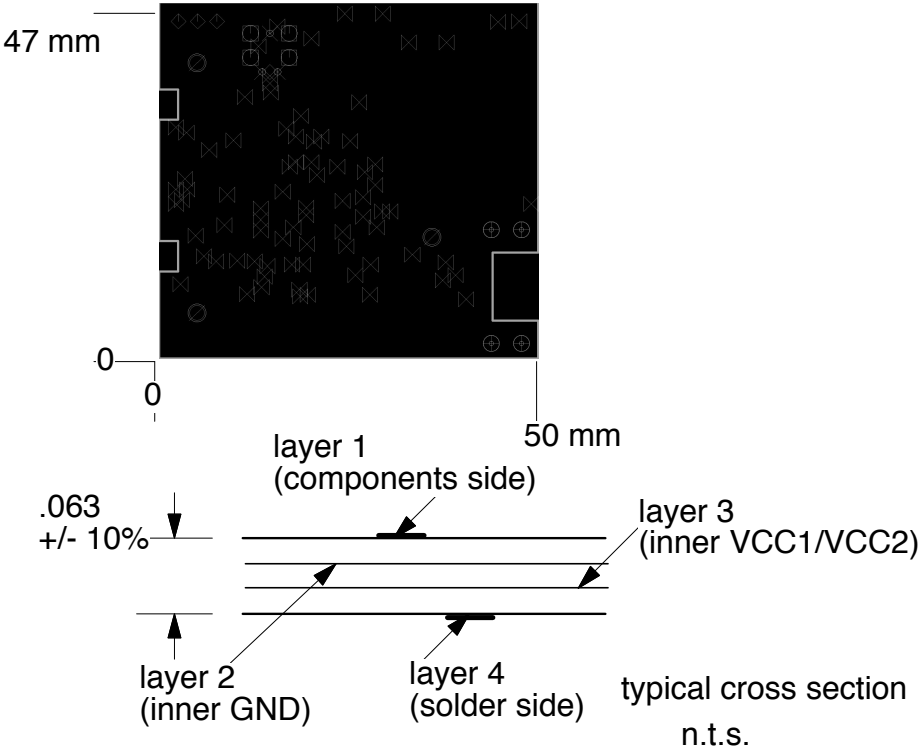


NOTES: Unless otherwise specified

1. All layers to be FR4 - 0.063" thick.
2. All copper layers shall be 1 Oz (1.4 mil) finished thickness.
3. Layer stack up as shown.
4. Solder mask both sides shall be vendor standard.
5. Silkscreen both sides shall be white.
6. Board twist and warp shall not exceed 7 mil/linear inch.
7. All vendor in-process marking must be placed on bottom side.
8. ENIG Plate on all pads.

size (mil) sym

24	+
35	×
83	□
40	◇
95	⊗
12	⊗
	↗
	↖
	✱
	✱
	▽
	△



ITEM	QTY	NAME	DESCRIPTION	SIZE
PARTS LIST AND DESCRIPTION				
TOLERANCES		<i>EtAL</i>		
.X		.50		
.XX		.25		
.XXX		.10		
UNLESS OTHERWISE SPECIFIED		Bryan & Andrew		
DRAWN	O.B.	FCSM NO	DWG NO	REV
ISSUED		SCALE	WEIGHT	SHEET 1